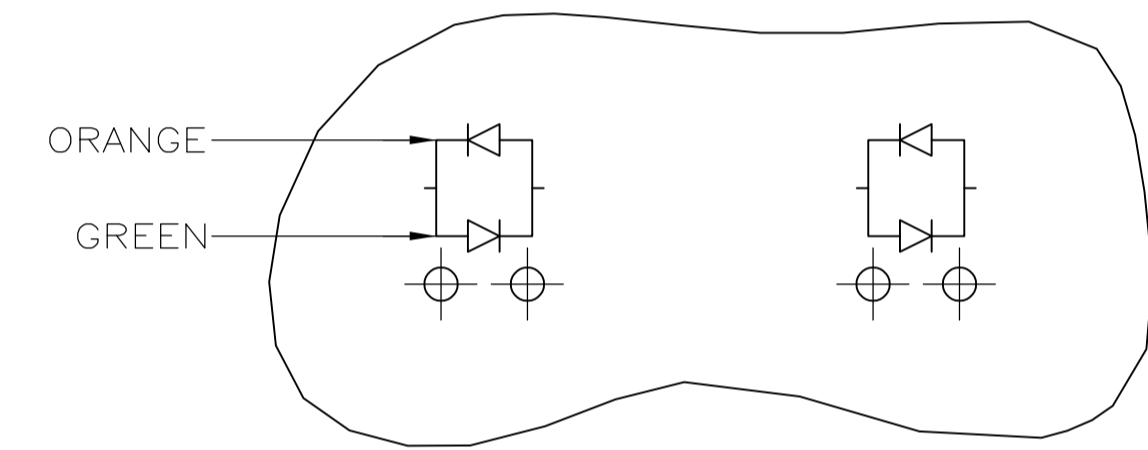
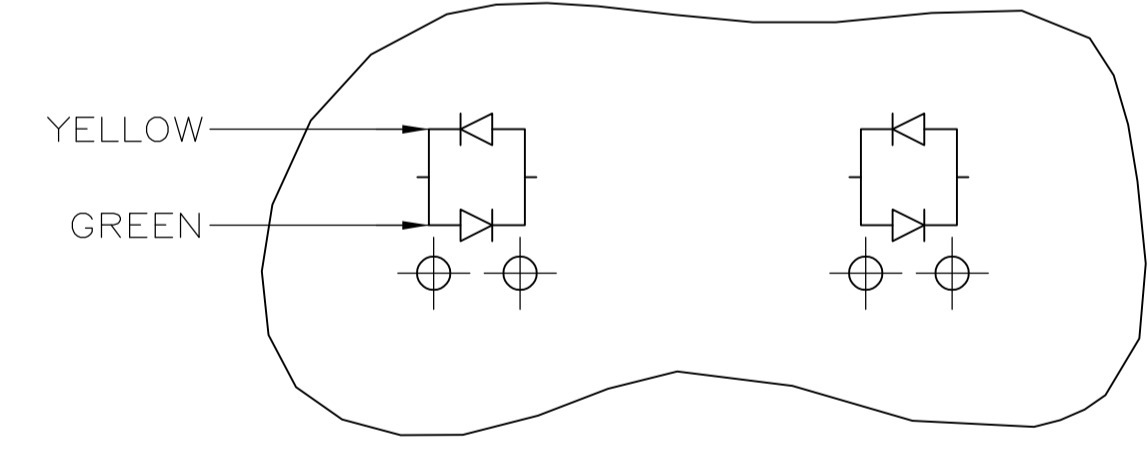


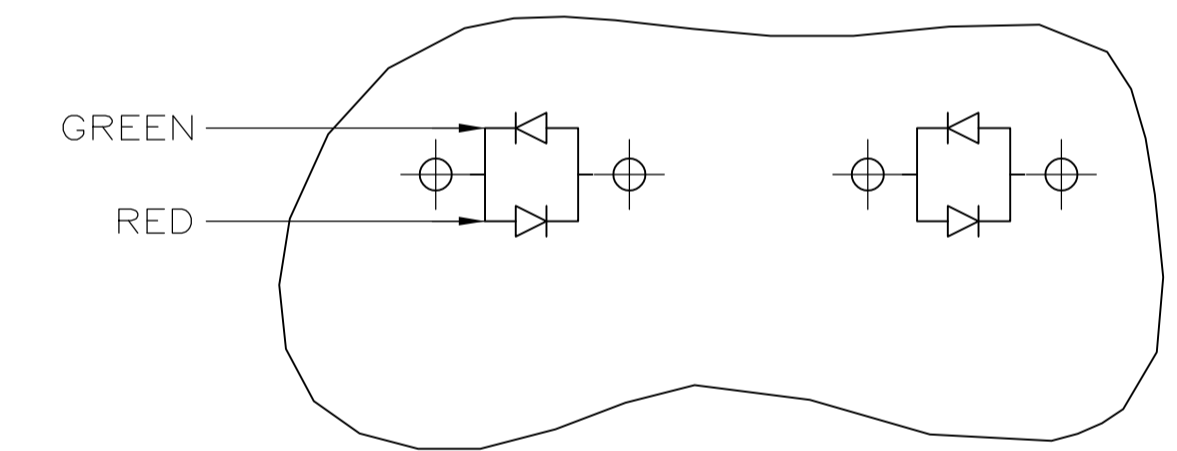
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.00050] MINIMUM THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.00050] MINIMUM SATIN NICKEL WITH 2.03µm[0.00080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm THICK Sn/Cu OVER 2.03µm THICK Ag OVER 1.02µm THICK Cu OVER 3.56µm THICK Ni OVER 1.02µm THICK Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI
- TAPE & REEL PACKAGING, FULLY ESD COMPLIANCE.



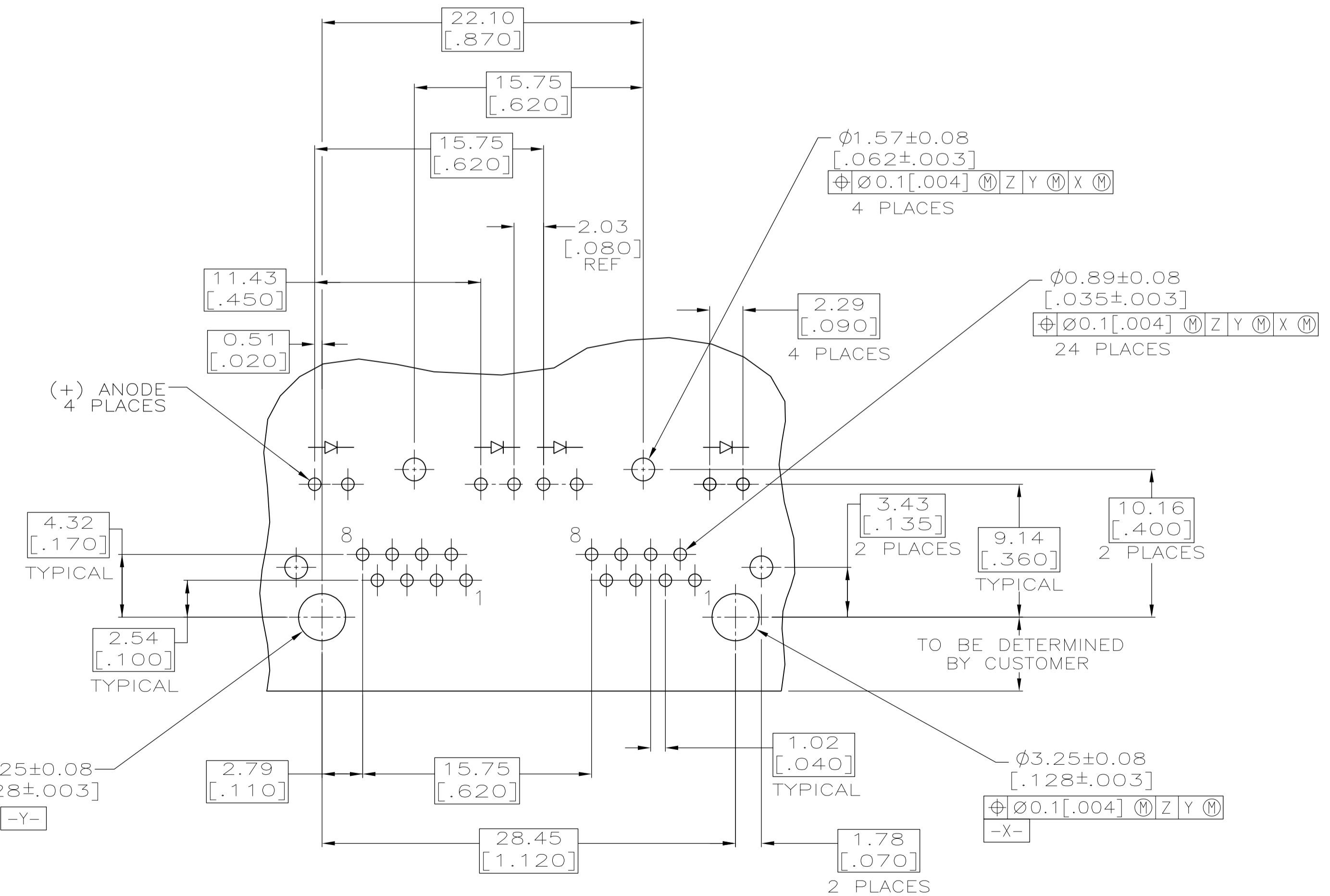
LED CURRENT DIAGRAM
6116353-7 ONLY



LED CURRENT DIAGRAM
6116353-8 ONLY



LED CURRENT DIAGRAM
1-6116353-3 & 2-6116353-9 ONLY



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
2.54 [.100]	YELLOW	GREEN	3-6116353-2
3.05 [.120]	YELLOW	GREEN	3-6116353-1
3.55 [.140]	RED/GREEN	RED/GREEN	2-6116353-9
3.05 [.120]	YELLOW/GREEN	YELLOW/GREEN	2-6116353-8
3.05 [.120]	GREEN	GREEN	2-6116353-4
2.54 [.100]	RED	YELLOW/GREEN	2-6116353-3
2.54 [.100]	RED/GREEN	RED/GREEN	1-6116353-3
3.55 [.140]	YELLOW	GREEN	6116353-9
2.54 [.100]	YELLOW/GREEN	YELLOW/GREEN	6116353-8
2.54 [.100]	ORANGE/GREEN	ORANGE/GREEN	6116353-7
2.54 [.100]	YELLOW	YELLOW	6116353-6
2.54 [.100]	GREEN	GREEN	6116353-5
2.54 [.100]	GREEN	YELLOW	6116353-4
2.54 [.100]	YELLOW	-	6116353-3
2.54 [.100]	-	GREEN	6116353-2
2.54 [.100]	YELLOW	GREEN	6116353-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIM: DL DRUMMOND/L.A.MAYER. CHK: J.WESTMAN. APVD: S.FLICKINGER. NAME: INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND, WITH LEDS. SIZE: A1. WEIGHT: -. SCALE: 4:1. SHEET: 1 OF 1. REV: E.

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)